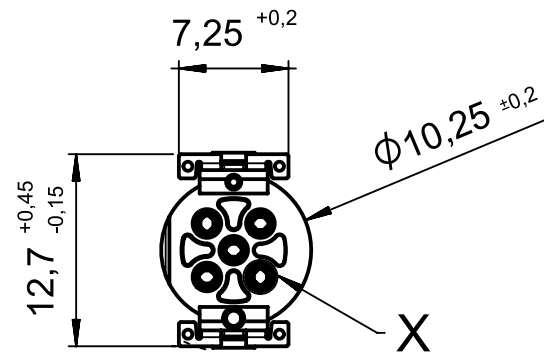
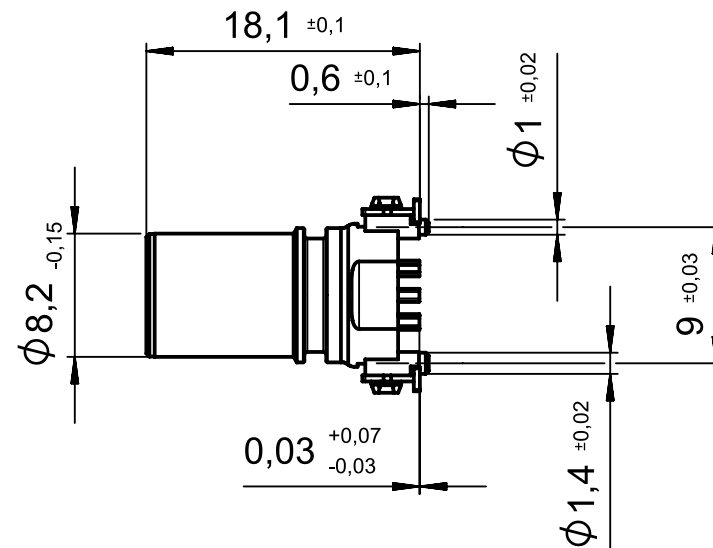
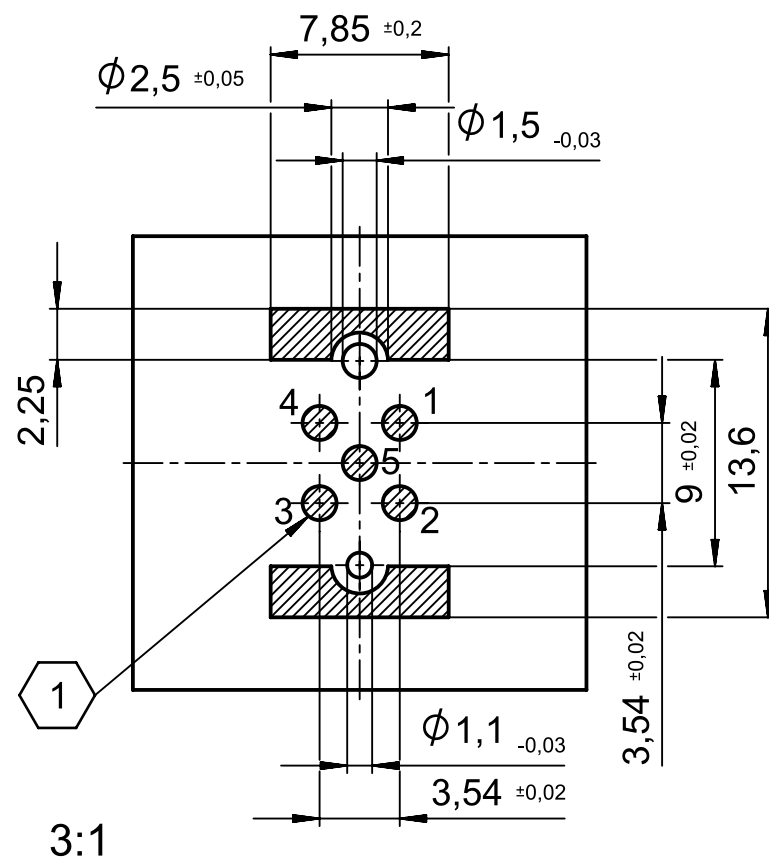


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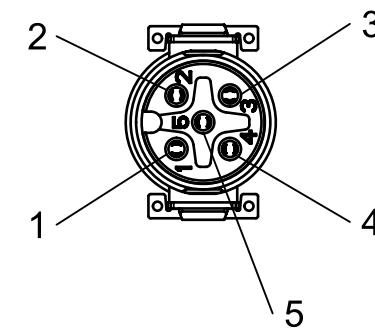
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PCB-layout
(advice)

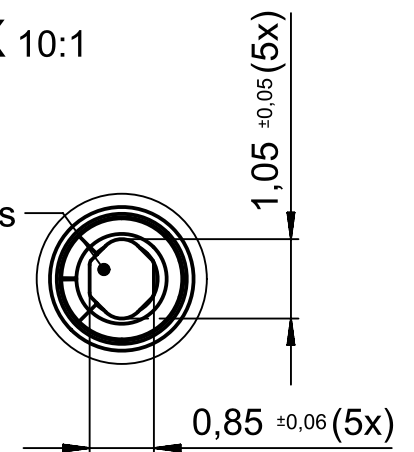


socket face female



X 10:1

orientation of the contacts varies



Coplanarity of all contacts and anchor plate $\square 0.1$

Recommended solder paste thickness 150 μ m

1 Further information on soldering process and recommended layout, see brochure "Connectors for SMT production"

- EN ISO 291 23/50

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			date 2025-10-27	document-type TECDOC 2D-Productdrawing		
description SACC-CI-M12FS-5P SMD R32						
page	1	of	1			

- EN ISO 291 23/50

- Simplified representation

- Linear dimensions (mm)

SACC-CI-M12FS-5P SMD R32